

Please amend the application as follows:

In the Claims:

Please cancel non-elected Claims 13-19 without prejudice.

Please amend the claims as follows:

1. (amended) A semiconductor device₁ including:

A¹ a chip having an array of flip chip contact terminals on the first surface thermo-compression bonded directly to mirroring contact pads on the first major surface of a substrate; and

a thermosetting adhesive polymerized by energy from infrared radiation of the second surface of said chip mechanically connecting and filling the space between the chip and substrate.

Please add the following new claims:

20. A semiconductor device, comprising:

a chip including an array of contact terminals;

a substrate including an array of contact pads, wherein said contact terminals are in direct contact with said contact pads; and

A² a thermosetting adhesive between said chip and said substrate and in contact with said contact terminals and said contact pads.

21. The semiconductor device of Claim 20, wherein said contact terminals and said contacts pads have a surface of gold.

22. The semiconductor device of Claim 20, wherein said thermosetting adhesive has a gel time in the range of 1 to 5 seconds.
